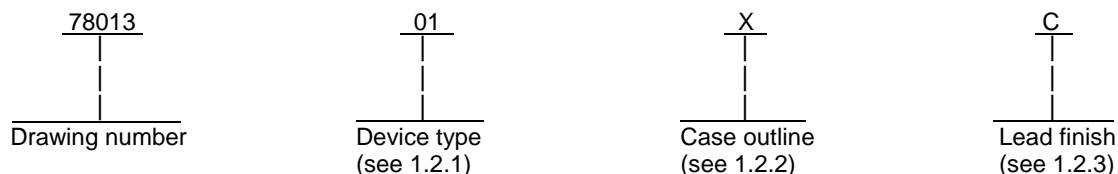


REVISIONS																			
LTR	DESCRIPTION												DATE (YR-MO-DA)				APPROVED		
A	Convert to approved source format; Change vendor.												82-04-01				N. A. Hauck		
B	Change test method references to 5008; Reinstate vendor, FSCM 27014.												82-05-14				W. E. Shoup		
C	Add vendor, FSCM 23223; Modify paragraph 3.7.												83-04-22				N. A. Hauck		
D	Add vendor's FSCM 63071 and 64762. Editorial changes throughout.												84-12-14				N. A. Hauck		
E	Page 2, add case outline. Page 6, add dimensions for optional base and seating plane.												85-08-30				N. A. Hauck		
F	Change to Military Drawing format. Remove vendor CAGE 13856.												87-02-13				W. Heckman		
G	Remove CAGE 63071. Changed to reflect MIL-H-38534 processing. Changed drawing CAGE to 67268.												90-05-09				W. Heckman		
H	Update document to current MIL-H-38534 requirements. Editorial changes throughout.												92-05-20				G. A. Lude		
J	Changes in accordance with NOR 5962-R126-94.												94-03-29				K. A. Cottongim		
K	Add vendor CAGE 51651. Change to table 1 and figure 1.												98-06-22				K. A. Cottongim		
L	Update drawing boilerplate.												04-02-23				Raymond Monnin		
<p>THE ORIGINAL FIRST SHEET OF THIS DRAWING HAS BEEN REPLACED.</p>																			
<p>CURRENT CAGE CODE 67268</p>																			
REV																			
SHEET																			
REV																			
SHEET																			
REV STATUS				REV				L	L	L	L	L	L	L	L				
OF SHEETS				SHEET				1	2	3	4	5	6	7	8	9			
PMIC N/A				PREPARED BY Joan M. Fisher								<p align="center">DEFENSE SUPPLY CENTER COLUMBUS POST OFFICE BOX 3990 COLUMBUS, OHIO 43216-5000 http://www.dscc.dla.mil</p>							
<p align="center">STANDARD MICROCIRCUIT DRAWING</p> <p align="center">THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE</p> <p align="center">AMSC N/A</p>				CHECKED BY C. R. Jackson															
				APPROVED BY N. A. Hauck								<p align="center">MICROCIRCUIT, HYBRID, LINEAR, HIGH CURRENT AMPLIFIER, THICK/THIN FILM</p>							
				DRAWING APPROVAL DATE 79-01-17															
				REVISION LEVEL L								SIZE A	CAGE CODE 14933		78013				
								SHEET 1 OF 9											

1. SCOPE

1.1 Scope. This drawing describes device requirements for class H hybrid microcircuits to be processed in accordance with MIL-PRF-38534 and a choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN).

1.2 PIN. The PIN shall be as shown in the following example:



1.2.1 Device type(s). The device type(s) shall identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	0002, MSK 0002H	Current amplifier

1.2.2 Case outline(s). The case outline(s) shall be as designated in MIL-STD-1835 and as follows: 1/

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
G	MACY1-X8	8	Can
X	See figure 1	8	Can

1.2.3 Lead finish. The lead finish shall be as specified in MIL-PRF-38534.

1.3 Absolute maximum ratings. 2/

Supply voltage (V _s).....	±22 V dc
Input voltage range.....	±22 V dc
Storage temperature range	-65°C to +150°C
Power dissipation (P _D), T _A = +25°C.....	600 mW 3/
Lead temperature (soldering, 10 seconds).....	+300°C
Thermal resistance, junction-to-case (θ _{JC})	40°C/W
Junction temperature (T _J)	+175°C

1.4 Recommended operating conditions.

Ambient operating temperature range (T _A).....	-55°C to +125°C
--	-----------------

1/ Use 7801301XX to replace older devices marked 7801301GX (date codes prior to 30 August 1985) for applications requiring the case outline described on figure 1 herein.

2/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

3/ No heat sink.

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2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation.

SPECIFICATION

DEPARTMENT OF DEFENSE

MIL-PRF-38534 - Hybrid Microcircuits, General Specification for.

STANDARDS

DEPARTMENT OF DEFENSE

MIL-STD-883 - Test Method Standard Microcircuits.

MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

HANDBOOKS

DEPARTMENT OF DEFENSE

MIL-HDBK-103 - List of Standard Microcircuit Drawings (SMD's).

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbooks are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 Item requirements. The individual item performance requirements for device class H shall be in accordance with MIL-PRF-38534. Compliance with MIL-PRF-38534 may include the performance of all tests herein or as designated in the device manufacturer's Quality Management (QM) plan or as designated for the applicable device class. Therefore, the tests and inspections herein may not be performed for the applicable device class (see MIL-PRF-38534). Furthermore, the manufacturers may take exceptions or use alternate methods to the tests and inspections herein and not perform them. However, the performance requirements as defined in MIL-PRF-38534 shall be met for the applicable device class. The modification in the QM plan shall not affect the form, fit, or function as described herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38534 and herein.

3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.2 herein and figure 1.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.

3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full specified operating temperature range.

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3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.

3.5 Marking of device(s). Marking of device(s) shall be in accordance with MIL-PRF-38534. The device shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's vendor similar PIN may also be marked.

3.6 Data. In addition to the general performance requirements of MIL-PRF-38534, the manufacturer of the device described herein shall maintain the electrical test data (variables format) from the initial quality conformance inspection group A lot sample, for each device type listed herein. Also, the data should include a summary of all parameters manually tested, and for those which, if any, are guaranteed. This data shall be maintained under document revision level control by the manufacturer and be made available to the preparing activity (DSCC-VA) upon request.

3.7 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to supply to this drawing. The certificate of compliance (original copy) submitted to DSCC-VA shall affirm that the manufacturer's product meets the performance requirements of MIL-PRF-38534 and herein.

3.8 Certificate of conformance. A certificate of conformance as required in MIL-PRF-38534 shall be provided with each lot of microcircuits delivered to this drawing.

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-PRF-38534 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

4.2 Screening. Screening shall be in accordance with MIL-PRF-38534. The following additional criteria shall apply:

- a. Pre-seal burn-in test, method 1030 of MIL-STD-883. (optional for class H)
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DSCC-VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1030 of MIL-STD-883.
 - (2) T_A as specified in accordance with table I of method 1015 of MIL-STD-883.
- b. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DSCC-VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
 - (2) T_A as specified in accordance with table I of method 1015 of MIL-STD-883.
- c. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

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TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions ^{1/} -55°C ≤ T _A ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
DC input offset current	I _{IO}	R _S = 10 kΩ, R _L = 1.0 kΩ	1,2,3	01	-10	+10	μA
DC input offset voltage	V _{IO}	R _S = 300 Ω, R _L = 1.0 kΩ	1,2,3	01	-30	+30	mV
Output voltage swing	V _O	V _{IN} = ±12 V, R _L = 1.0 kΩ, T _A = +25°C	4	01	±10		V
		V _{IN} = ±10 V, R _L = 100Ω, V _S = ±15 V, T _A = +25°C			±9.5		
Supply currents	+I _{CC}	R _S = 10 kΩ, R _L = 1.0 kΩ V _{IN} = 0 V, T _A = +25°C	1	01		+10.0	mA
	-I _{CC}				-10.0		
Voltage gain	A _V	V _{IN} = 3.0 Vp-p, R _S = 10 kΩ, R _L = 1.0 kΩ, f = 1.0 kHz	4,5,6 <u>2/</u>	01	0.95		V/V
Input impedance <u>3/</u>	Z _{IN}	V _{IN} = 1.0 V rms, R _S = 200 kΩ, R _L = 1.0 kΩ, f = 1.0 kHz, T _A = +25°C	4	01	180		kΩ
Output impedance <u>3/</u>	Z _{OUT}	V _{IN} = 1.0 V rms, R _S = 10 kΩ, R _L = 50 Ω, f = 1.0 kHz, T _A = +25°C	4	01		10	Ω
Rise time	t _r	V _{OUT} = 2.5 Vp-p, R _S = 100 kΩ, R _L = 50 Ω, T _A = +25°C	4	01		12	ns

^{1/} V_S = ±12 V, unless otherwise specified.^{2/} Subgroups 5 and 6 shall be tested as part of device initial characterization and after design and process changes. Parameter shall be guaranteed to the limits specified for subgroups 5 and 6 for all lots not specifically tested.^{3/} Parameter and limits specified shall be guaranteed, but not tested.**STANDARD
MICROCIRCUIT DRAWING**DEFENSE SUPPLY CENTER COLUMBUS
COLUMBUS, OHIO 43216-5000SIZE
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L**78013**SHEET
5

Case outline X.

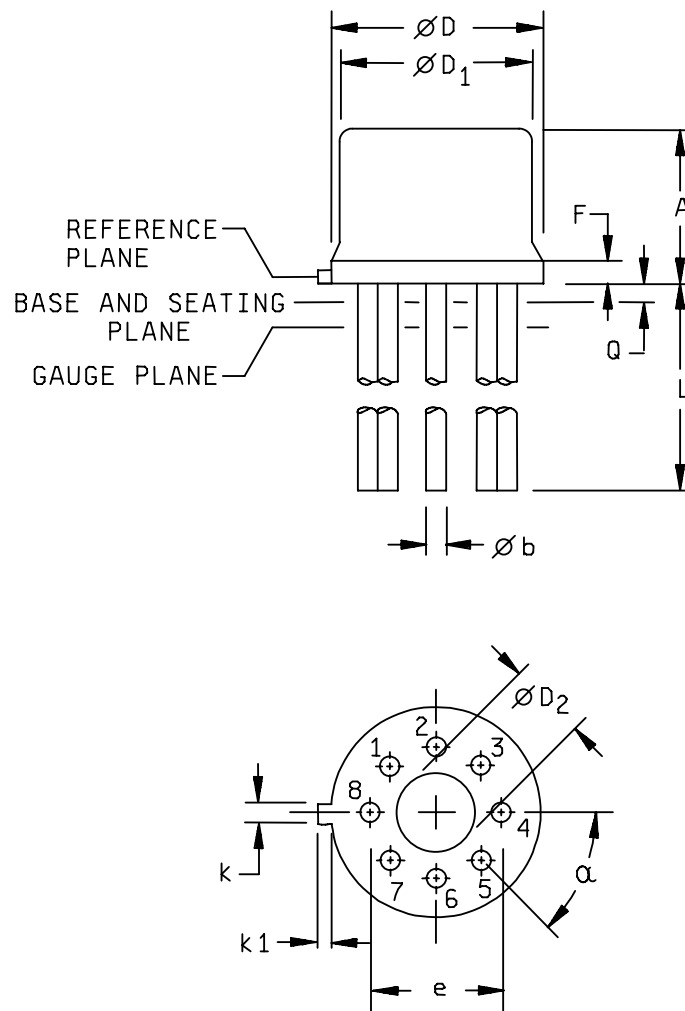


FIGURE 1. Case outline(s).

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Case outline X - Continued.

Symbol	Inches		Millimeters		Notes
	Min	Max	Min	Max	
A	0.155	0.185	3.94	4.70	4
Øb	0.015	0.019	0.38	0.48	
ØD	0.335	0.370	8.51	9.40	
ØD ₁	0.305	0.335	7.75	8.51	5
ØD ₂	0.110	0.160	2.79	4.06	
e	0.230 BSC		5.84 BSC		
F	---	0.040	---	1.02	6
k	0.027	0.034	0.69	0.86	
k ₁	0.027	0.045	0.69	1.14	
L	0.500	0.750	12.70	19.05	5
Q	---	0.050	---	1.27	
α	45° BSC		45° BSC		

NOTES:

1. Dimensions are in inches
2. Metric equivalents are given for general information only.
3. The product may be measured by direct methods or by gauge.
4. All leads: Increase maximum limit by .003 inch (0.08 mm) when lead finish A is applied.
5. Optional base and seating plane.
6. Measured from the maximum diameter of the product.

FIGURE 1. Case outline(s) -Continued.

Device type	01
Case outlines	G and X
Terminal number	Terminal symbol
1	V ₁ +
2	V ₂ +
3	E ₃
4	Output
5	E ₄
6	V ₂ -
7	V ₁ -
8	Input

FIGURE 2. Terminal connections.

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TABLE II. Electrical test requirements.

MIL-PRF-38534 test requirements	Subgroups (in accordance with MIL-PRF-38534, group A test table)
Interim electrical parameters	---
Final electrical parameters	1*, 2, 3, 4, 5, 6
Group A test requirements	1, 2, 3, 4
Group C end-point electrical parameters	1, 2, 3, 4

* PDA applies to subgroup 1.

4.3 Conformance and periodic inspections. Conformance inspection (CI) and periodic inspection (PI) shall be in accordance with MIL-PRF-38534 and as specified herein.

4.3.1 Group A inspection (CI). Group A inspection shall be in accordance with MIL-PRF-38534 and as follows:

- a. Tests shall be as specified in table II herein.
- b. Subgroups 7, 8, 9, 10, and 11 shall be omitted.

4.3.2 Group B inspection (PI). Group B inspection shall be in accordance with MIL-PRF-38534.

4.3.3 Group C inspection (PI). Group C inspection shall be in accordance with MIL-PRF-38534 and as follows:

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DSCC-VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - (2) T_A as specified in accordance with table I of method 1005 of MIL-STD-883.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.3.4 Group D inspection (PI). Group D inspection shall be in accordance with MIL-PRF-38534.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38534.

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6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-PRF-38534.

6.4 Record of users. Military and industrial users shall inform Defense Supply Center Columbus when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0544.

6.5 Comments. Comments on this drawing should be directed to DSCC-VA, Post Office Box 3990, Columbus, Ohio 43216-5000, or telephone (614) 692-1081.

6.6 Sources of supply. Sources of supply are listed in MIL-HDBK-103 and QML-38534. The vendors listed in MIL-HDBK-103 and QML-38534 have submitted a certificate of compliance (see 3.7 herein) to DSCC-VA and have agreed to this drawing.

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STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 04-02-23

Approved sources of supply for SMD 78013 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38534 during the next revisions. MIL-HDBK-103 and QML-38534 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revisions of MIL-HDBK-103 and QML-38534.

Standard microcircuit drawing PIN <u>1/</u>	Vendor CAGE number	Vendor similar PIN <u>2/</u>
7801301GA	<u>3/</u>	CTS0002 (GEN)
7801301XA 7801301XC	13409 13409	SEN-0002H SEN-0002H
7801301XA	27851	FLH0002H/883
7801301XA 7801301XC	51651 51651	MSK 0002H MSK 0002H

- 1/ The lead finish shown for each PIN, representing a hermetic package, is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the Vendor to determine availability.
- 2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ Not available from a QML source.

Vendor CAGE
numberVendor name
and address

13409

Sensitron Semiconductor
221 West Industry Court
Deer Park, NY 11729

27851

Satcon Electronics
165 Cedar Hill Street
Marlborough, MA 01752

51651

M. S. Kennedy Corporation
4707 Dey Road
Liverpool, NY 13088

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